

DATE: 24 January, 2025

PCN #: 2711

PCN Title: Additional Wafer Sources and Transfer of Wafer Manufacturing Site for Select Discrete Products

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of notification by contacting your local Diodes sales representative. If you require samples for evaluation purposes, please submit a corresponding request within 30 days as well. Otherwise, samples may not be built prior to the implementation of the announced change(s).

The change(s) announced in this PCN will not be implemented prior to the target implementation date, i.e. 90 days from the stated notification date, unless Diodes receives written customer approval before that date.

Previously agreed upon customer specific product and/or process change requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2711-REV1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:					
24 January, 2025	24 April, 2025	Discrete Semiconductor	Additional Wafer Source, Metallization System	2711					
TITLE									
Addit	ional Wafer Sources and T	ransfer of Wafer Manufacturin	ng Site for Select Discrete Pro	oducts					
DESCRIPTION OF CHANGE									
 This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified the following wafer source changes for selecting discrete products listed below. Diodes internal wafer fabrication source (JKFAB) in Hsinchu, Taiwan as additional wafer source, and Diodes internal assembly and test site (CAT) located in Chengdu, China for processing wafer top metal (TM) and back metal (BM). Diodes internal wafer fabrication (fab) source WX1 in Wuxi, China as new wafer source. Affected products will be transferred from Diodes internal wafer fabrication source SSEC in Shanghai, China to WX1 fab. Full electrical characterization and reliability testing have been completed on representative part numbers to ensure there is no change to product reliability, device functionality or electrical specifications in the datasheet. There will be no change to the Form, Fit, or Function of affected products. 									
	Ν	o change in datasheet parame	eters						
		PRODUCTS AFFECTED							
Table 1 – Affected part list to add JKFAB as additional wafer source, and add CAT for TM and BM Table 2 – Affected part list to transfer to WX1 FAB as new wafer source WEB LINKS									
Manufacturer's Notic	ce: https://	www.diodes.com/quality/produ	uct-change-notices/diodes-pr	oduct-change-notices/					
For More Informatio		https://www.diodes.com/about/contact-us/contact-sales/							
Data Sheet:		https://www.diodes.com/catalog/							
DISCLAIMER									
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days from the notification date of this PCN, all changes described in this announcement are considered approved.									



Table 1 - Affected part list to add JKFAB as additional wafer source, and add CAT for TM and BM								
DFLT26A-7	DFLT28A-7	DFLT33A-7	DFLT40A-7	DFLT45A-7	DFLT51A-7			
DFLT27A-7	DFLT30A-7	DFLT36A-7	DFLT43A-7	DFLT48A-7				

Table 2 - Affected part list to transfer to WX1 FAB as new wafer source								
FU1KA_HF	FUS1ME	UG1005_HF	UG2007_HF	US1J-13-F	US1M-13-F			
FUS1JD_HF	FUS1ME-7	UG1007_HF	UG2007_HF-A52	US1K_HF	US2K_HF			
FUS1JE-7	FUS2MD_HF	UG1007_HF-A52	UG3007_HF	US1K-13-F	US2M_HF			
FUS1MD_HF	UD7G_HF	UG2006_HF-A52	US1J_HF	US1M_HF				